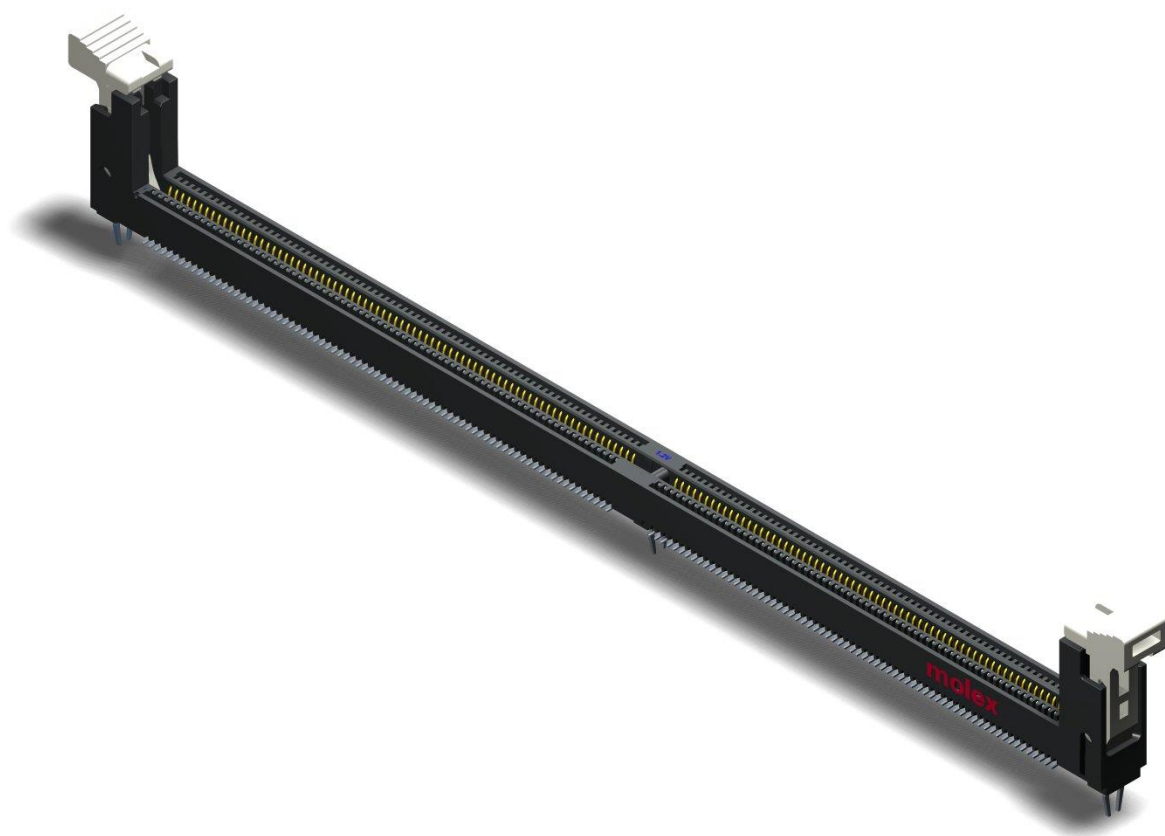


DDR4 DIMM SOCKET >

VERTICAL SMT 288CKT



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CHANGE NO.	734567			DDR4 DIMM, 0.85MM PITCH, 288CKTS, VERTICAL SMT			
REVISED BY	LIMONL	DATE	2023/01/06	DOC TYPE	DOC TYPE DESCRIPTION	DOC PART	SERIES
REV APPR BY	SHLENI	DATE	2023/01/22	PS	PRODUCT SPECIFICATION WORD	001	78730
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1.0 SCOPE

This specification covers the processing guidelines and the requirements for the application of a DDR4 Dual In-line Memory Module (DIMM) 288-circuit connector with SMT solder tail design.

All dimensional values shown are in metric units. Any figure and illustration found in this document are for graphical representation only and are not drawn to scale.

The connectors are available in 288-pin type with contact spacing on 0.85mm pitch centerline. These connectors are designed to connect memory module cards of 1.40mm thickness (Daughter Card) as per JEDEC MO-309 to Printed Circuit Boards (PCB).

When corresponding with a Molex Personnel, kindly use the terminology provided in this document to facilitate your request for more information. Basic terms and features of this product are illustrated in Figure 1.

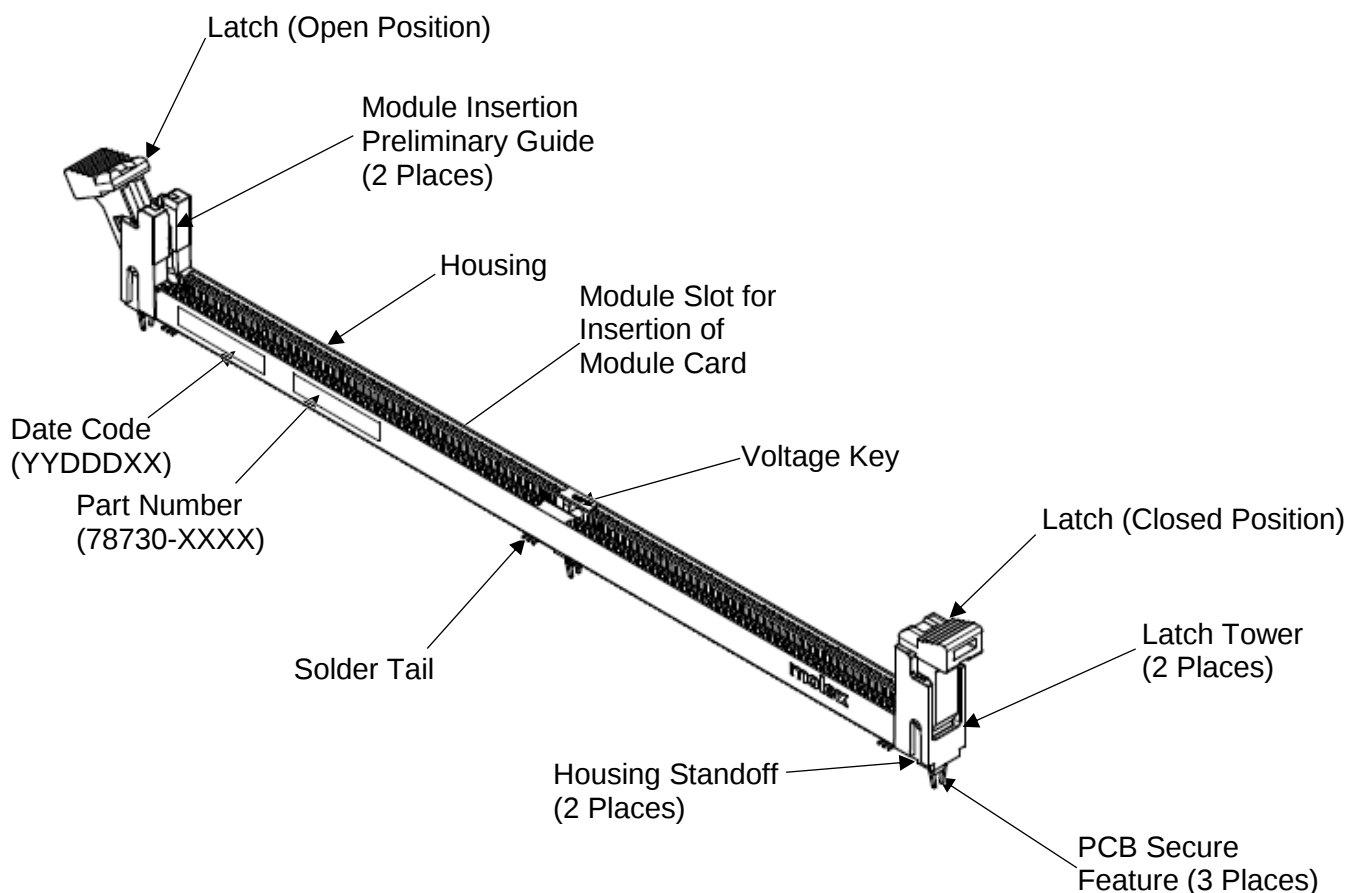


Figure 1: DDR4 DIMM 288ckts SMT connector

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2.0 PRODUCT DESCRIPTIONS

2.1 PRODUCT DESCRIPTIONS AND PART NUMBERS

SERIES NUMBER	DESCRIPTION
78730	DDR4 DIMM, 0.85mm PITCH, VERTICAL, SMT, 288CKT
78839	DDR4 DIMM, 0.85mm PITCH, VERTICAL, AERO, SMT, 288CKT
151004	DDR4 DIMM, 0.85mm PITCH, VERTICAL, AERO, SMT, 288CKT
204245	DDR4 DIMM, 0.85mm PITCH, VERTICAL, SMT, 288CKT
212825	DDR4 DIMM, 0.85mm PITCH, VERTICAL, SMT, 288CKT

The above series numbers are shown for reference only. This application guideline shall apply to all products with part numbers that fall under the families of 78730, 78839, 151004, 204245 and 212825.

This document is not intended to be the final process definition nor is it intended to constrain design.

3.0 REFERENCE DOCUMENTS

3.1 DRAWINGS

Sales drawings are available from the Molex service network. See the appropriate Sales Drawings for information on dimensions, materials, plating and markings, recommended module outlines and footprint specifications.

In the event of any discrepancy between the information contained in the Sales Drawings and this specification or with any other technical documentation supplied, the Sales Drawings take precedence.

3.2 SPECIFICATIONS

Product Specifications provide detailed information on the product performance requirements and testing methodology. All test data collected will be used to compile test reports for evaluation purposes. Copies of these specifications are available upon request from a local Molex representative.

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4.0 PROCEDURE

4.1 GENERAL REQUIREMENTS

4.1.1 PACKAGING FOR INCOMING CONNECTOR

As the DDR4 DIMM SMT 288ckt connectors contain certain moisture-sensitive components, they will be sealed in moisture barrier bags with desiccant material enclosed. A label indicated "moisture sensitive" will be affixed to the immediate package near the Product Package Label to indicate the presence of moisture-sensitive components.

4.1.2 CONNECTOR MATERIAL

The housing is made from high temperature polyamide. The contacts are made from copper alloy with gold over nickel plating on its contact area and tin over nickel on its SMT solder tails. PCB secure features are made from copper alloy and the latches are made from high temperature polyamide.

4.1.3 FLOOR LIFE

The recommended floor life of the connectors is 168 hours at an ambient temperature of less than 30°C and a humidity level of less than 60% RH. It is recommended to use the components within 24 hours from opening the sealed original package. Unused quantities should be vacuum-sealed prior to storage for future use.

4.1.4 PCB LAYOUT

The connector can either be placed on a copper-defined or solder mask-defined pad which can be either coated with an organic protective coating or HASL. The dimensions of the pads can be found from the connectors' respective Sales Drawings.

Vias should not be placed in pads. A solder dam should be created using solder mask when a land goes to a via which is close to the pad, this will avoid wicking of the solder from the pad into the via.

4.1.5 SOLDER PASTE REQUIREMENTS

Lead-free solder past should be used. Rosin, mildly active (RMA) flux can be incorporated into the paste. For ease of use, a no-clean paste is recommended but the

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connector is also capable of being used with either Water Soluble (WS) or Rosin-based pastes

4.1.6 SOLDER PASTE DEPOSITION

The aperture of the stencil is dependant on the circuit pad size and stencil thickness. The stencil thickness should not be less than 0.10mm, with a preferred thickness of 0.15mm. A stencil aperture size of at least 90% of the pad size should be used. When a thinner stencil is used, the apertures may have to be enlarged slightly to facilitate sufficient paste deposition and ensure a good joint.

4.1.7 PLACEMENT

The connector will be supplied in plastic trays. The connector should only be handled by the housing to prevent any unintentional damage to the solder tails. Connectors should be placed with enough pressure to overcome the insertion force of the PCB secure feature into the PCB so that the solder tails touch down on the copper pads. A placement machine may be used for this operation, or manual insertion can be used should the placement be unsatisfactory by machine.

Irrespective of the placement method used, care should be taken to ensure the PCB secure features are completely engaged and the leads pushed down onto the copper pads.

4.1.8 SOLDER REFLOW

The PCB containing the connector should be reflowed using a reflow profile which is in compliance with the manufacturer's datasheet for the paste used or as per the product specification for the particular series. For Molex recommended reflow profile, please refer to the respective product specification.

It is recommended that the soak time be long enough to allow the temperature over the whole area under the connector to stabilize, while the time above liquidus be long enough for total reflow.

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This component is suitable for processing through the temperatures used in lead-free processes but should not be subjected to temperatures exceeding 260°C.

It is recommended that the connector be clamped with a jig (as illustrated in Figure 2A) or held down with a weight during reflow to ensure a good joint and prevent any open solder.

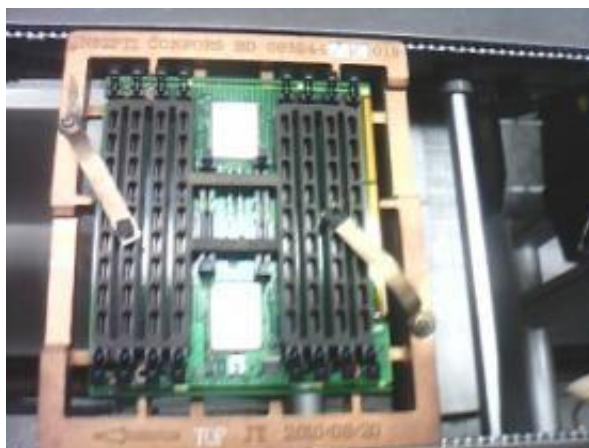


Figure 2A: Clamp-down Jig

Before putting the connectors through the reflow process, it is good practice to ensure the latches are fully closed as shown below in Figure 2B.

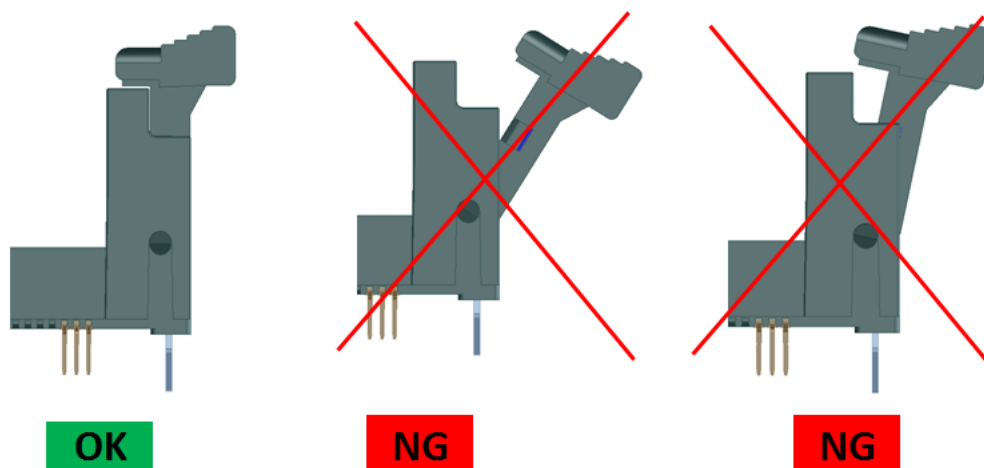


Figure 2B: Latch in Closed Position

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As shown in Figure 2C below, it is generally recommended that the orientation of the connectors to be placed perpendicular to the direction moving into the reflow oven. This is to encourage a better heat distribution to the connectors, optimizing and minimizing the bow during the reflow process.

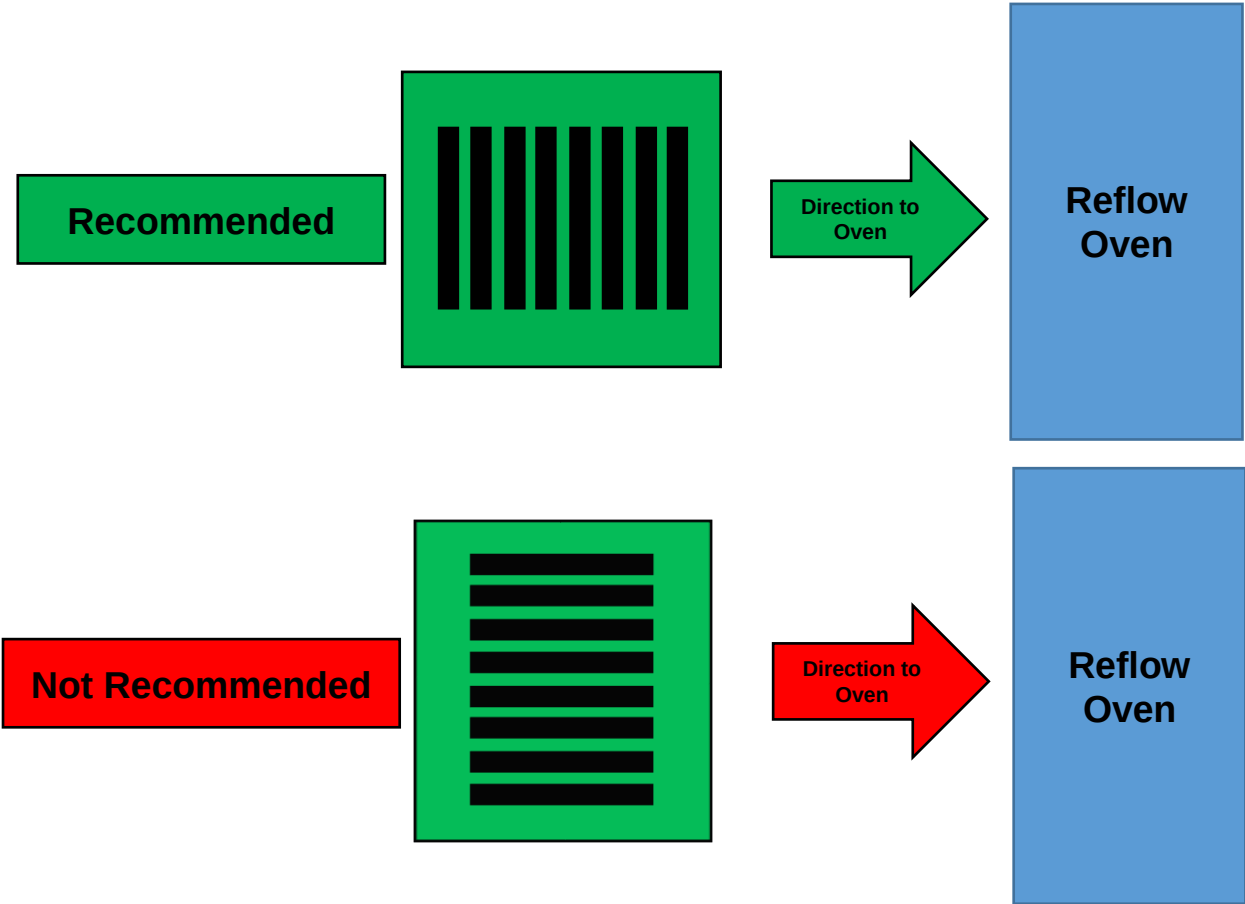


Figure 2C: Recommended Orientation of Connectors into Reflow Oven

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4.1.9 TWO-PASS REFLOW

Under normal conditions, this part is suitable for double-sided applications.

4.1.10 CLEANING

The connectors may be air blown to remove any residue or contaminants. External cleaning may also be done using industrial alcohol. However, care should be taken to ensure that the connectors are completely dry before electrical testing.

4.1.11 DISCOLORATION OF NATURAL (OFF-WHITE) COLOURED LATCHES/HOUSING

The connectors may be using natural (off-white) colored components for the housing or latches. These components may discolour or become yellowish. If discoloration is an appearance defect, it is recommended to purge with Nitrogen during the reflow process to minimize discoloration or choose the black colour option for these components.

4.2 ASSEMBLY INSTRUCTIONS**4.2.1 POST-APPLICATION INSPECTION**

The connector may be examined visually for damage and cleanliness. The solder joints can be inspected both visually and by using an X-ray equipment. The final testing would probably be using electrical test equipment for both in-circuit and application testing. However, care should be taken such that the design of this equipment does not cause damage to the housing or the terminals.

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4.3 REWORK AND REPAIR INSTRUCTIONS

It is recommended that a commercially available hot air rework station be used for the repair of this product. Many of these repair stations are readily available and the choice of manufacturer is to the discretion of the user. It is very important that the correct nozzle be used for this operation.

Depending on the card thickness and stack-up, in some circumstances, it may be recommended to pre-heat to 100°C on board gradually and hold for at least 60 minutes to avoid thermal shock to the PCB. It is recommended to shield adjacent components especially component body and solder joints during the rework process to avoid overheating and melting of the joints.

For removal process, this connector should be removed manually. To avoid additional heat cycle, excess solder should be removed from the site immediately after the connector is lifted off, while the board is still hot. A hand-held solder vacuum tool or solder wicking braid can be used. Both methods should only be performed by qualified operators. This is because damage to the board or pads is the greatest concern. After the removal, the connector should be discarded as it cannot be reused.

Before replacing with a new connector, the residual solder on the pads should be removed using either a vacuum scavenging system or by hand by a skilled operator. The solder pads should then be cleaned with alcohol and brush to ensure a clean surface. It is recommended that the pads be pasted again using a 0.15mm stencil. Once the new connector has been placed on the PCB, it should be reflowed.

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4.4 MODULE CARD MATING AND UNMATING INSTRUCTIONS

4.4.1 MODULE CARD MATING

The module card should be mated to the connector according to the following sequence (graphically represented in Figure 3):

- The latches of the connector must be fully open.
- The keying feature of the module card must be aligned with the voltage key of the connector.
- The sides of the module card must slide along the module insertion preliminary guides and into the module slot. The latches are designed in such a way that upon correct insertion of the module cards, they will rotate inwards to snap into the grooves located on the module card to secure it in place.
- Ensure that the module card is perpendicularly aligned to the connector before insertion as any misalignment may cause potential damage to the housing or contacts.
- The module card must be fully seated and the latches should be in the closed position.

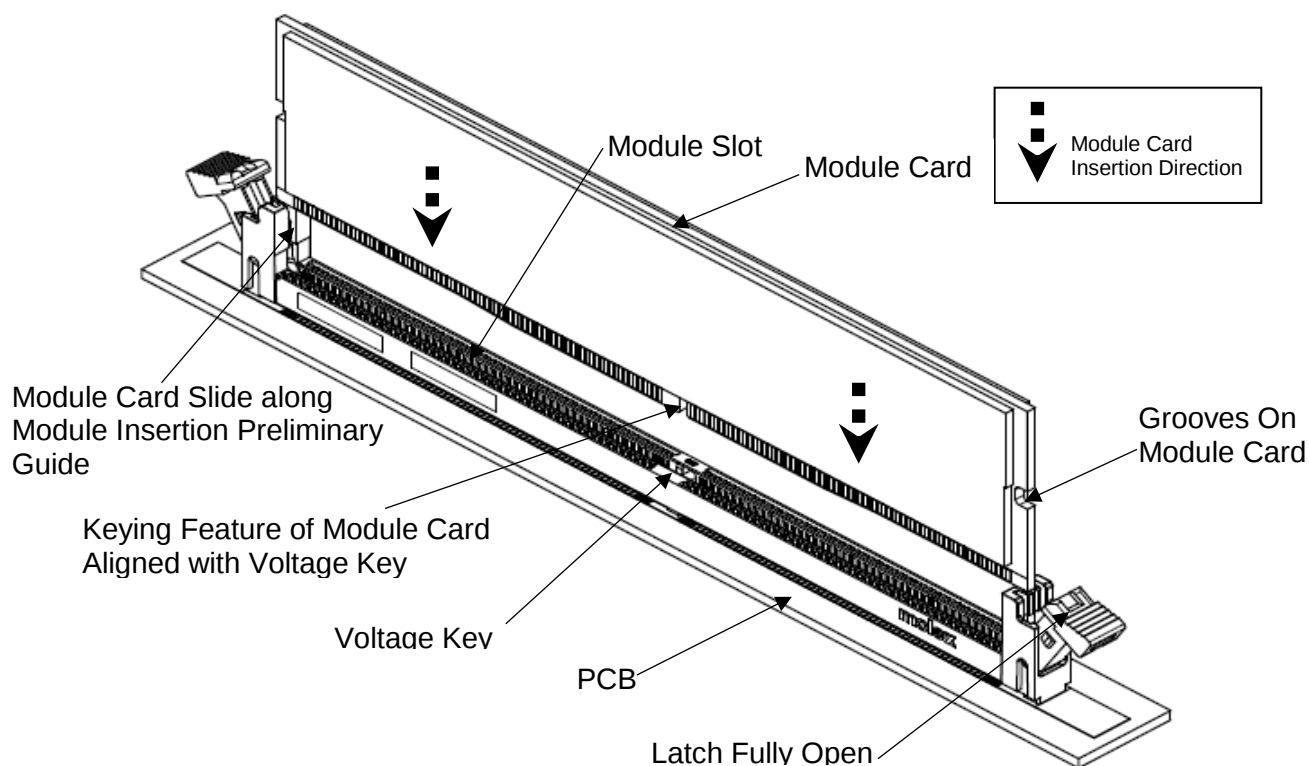


Figure 3: Graphical Representation of Proper Mating Layout

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4.4.2 MODULE CARD UNMATING

The module card should be unmated from the connector according to the following sequence (graphically represented in Figure 4):

- A. Both latches of the connector must be rotated away from the module card simultaneously. As the latches rotate, the module card will be ejected out from its seated slot. Upon opening the latches to their maximum position, the module card should be fully disengaged from the connector.
- B. The module card will be guided by the module insertion preliminary guides and slide out of the latch tower.

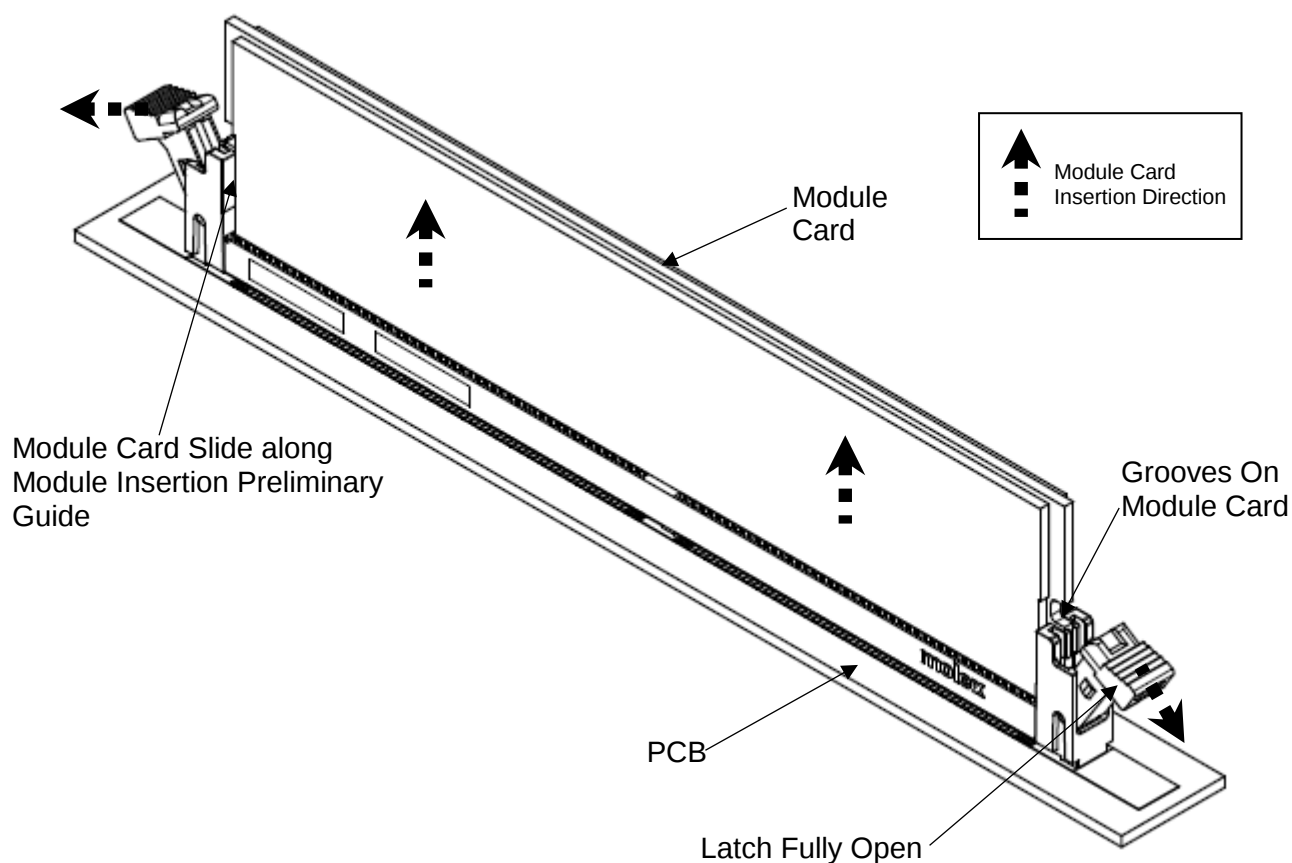


Figure 4: Graphical Representation of Proper Unmating Layout

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5.0 VISUAL INSPECTION

Figure 5 below illustrates the correct application of a DDR4 DIMM Vertical SMT 288ckt connector with the PCB and module card. Several key points listed below may be used as a guide to ensure correct application of this connector.

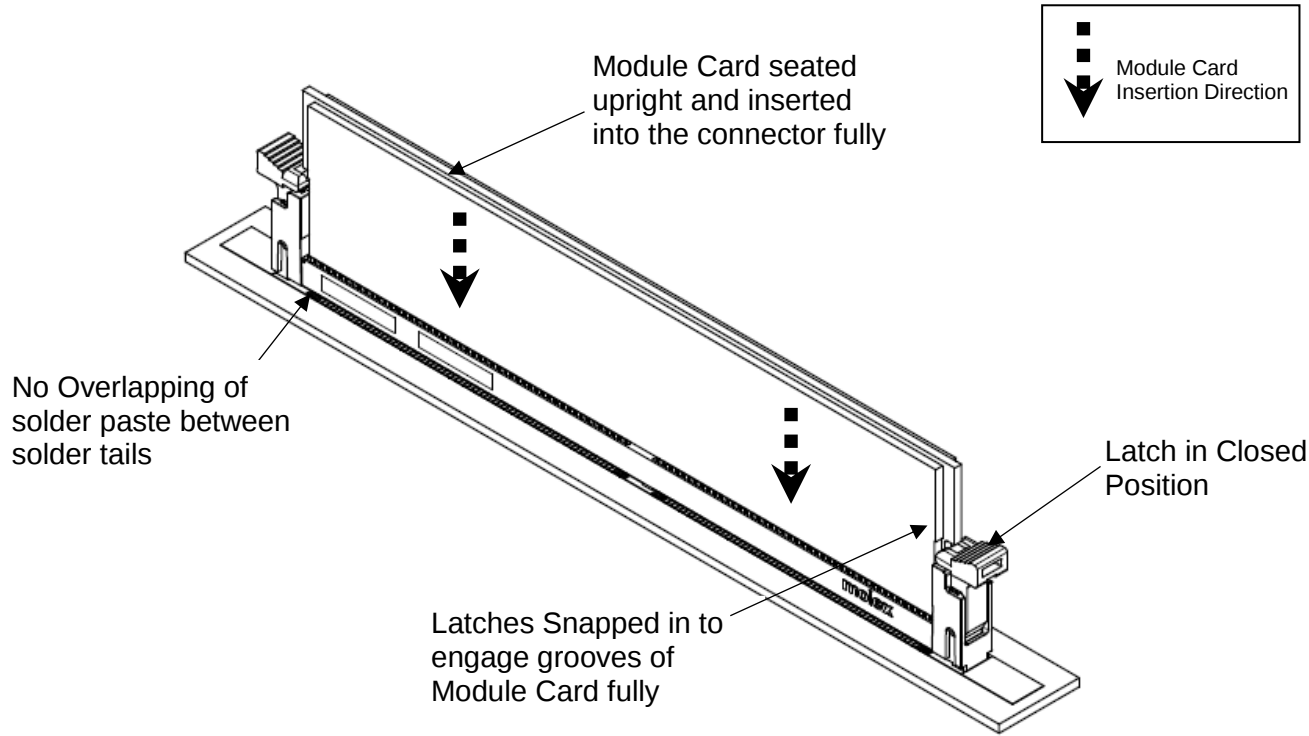


Figure 5: Correct Application of the DDR4 DIMM 288ckts SMT Connector, PCB and Module Card Assembly

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